

# 2.5 V or 3.3 V, 200 MHz, 1:12 Clock Distribution Buffer

#### **Features**

- 2.5 V or 3.3 V operation
- 200 MHz clock support
- LVPECL or LVCMOS/LVTTL clock input
- LVCMOS-/LVTTL-compatible inputs
- 12 clock outputs: drive up to 24 clock lines
- Synchronous Output Enable
- Output three-state control
- 150 ps typical output-to-output skew
- Pin compatible with MPC948, MPC948L, MPC9448
- Available in Commercial and Industrial temp. range
- 32-pin TQFP package

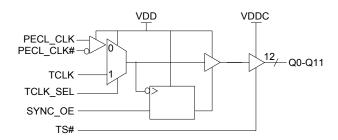
# **Functional Description**

The CY29948 is a low-voltage 200 MHz clock distribution buffer with the capability to select either a differential LVPECL or a LVCMOS/LVTTL compatible input clock. The two clock sources can be used to provide for a test clock as well as the primary system clock. All other control inputs are LVCMOS/LVTTL compatible. The 12 outputs are LVCMOS or LVTTL compatible and can drive 50  $\Omega$  series or parallel terminated transmission lines. For series terminated transmission lines, each output can drive one or two traces giving the device an effective fanout of 1:24. The outputs can also be three-stated via the three-state input TS#. Low output-to-output skews make the CY29948 an ideal clock distribution buffer for nested clock trees in the most demanding of synchronous systems.

The CY29948 also provides a synchronous output enable input for enabling or disabling the output clocks. Since this input is internally synchronized to the input clock, potential output glitching or runt pulse generation is eliminated.

For a complete list of related documentation, click here.

# **Block Diagram**





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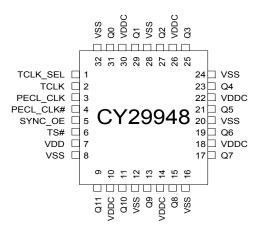
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# **Pin Configuration**

Figure 1. 32-pin TQFP pinout



# **Pin Description**

Pin	Name	PWR	I/O [1]	Description
3	PECL_CLK	-	I, PU	PECL Input Clock
4	PECL_CLK#	_	I, PD	PECL Input Clock
2	TCLK	_	I, PU External Reference/Test Clock Input	
9, 11, 13, 15, 17, 19, 21, 23, 25, 27, 29, 31	Q(11:0)	VDDC	O Clock Outputs	
1	TCLK_SEL	_	I, PU	Clock Select Input. When LOW, PECL clock is selected. When HIGH TCLK is selected.
5	SYNC_OE	_	I, PU Output Enable Input. When asserted HIGH, the outputs are ena	
6	TS#	_	I, PU	Three-state Control Input. When asserted LOW, the output buffers are three-stated. When set HIGH, the output buffers are enabled.
10, 14, 18, 22, 26, 30	VDDC	-	2.5 V or 3.3 V Power Supply for Output Clock Buffers	
7	VDD	-	_	2.5 V or 3.3 V Power Supply
8, 12, 16, 20, 24, 28, 32	VSS	_	_	Common Ground

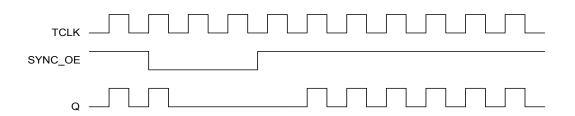
Note
1. PD = Internal pull-down, PU = Internal pull-up.



# **Output Enable/Disable**

The CY29948 features a control input to enable or disable the outputs. This data is latched on the falling edge of the input clock. When SYNC\_OE is asserted LOW, the outputs are disabled in a LOW state. When SYNC\_OE is set HIGH, the outputs are enabled as shown in Figure 2.

Figure 2. SYNC\_OE Timing Diagram





# **Maximum Ratings**

Exceeding maximum ratings [2] may shorten the useful life of the device. User guidelines are not tested.

Maximum Input Voltage Relative to V <sub>SS</sub>	$V_{SS} - 0.3 V$
Maximum Input Voltage Relative to $V_{DD} \dots$	V <sub>DD</sub> + 0.3 V
Storage Temperature	-65 °C to + 150 °C
Operating Temperature	. –40 °C to +85 °C
Maximum ESD protection	2 kV

Maximum Power Supply	5.5 V
Maximum Input Current	±20 mA

This device contains circuitry to protect the inputs against damage due to high static voltages or electric field; however, precautions should be taken to avoid application of any voltage higher than the maximum rated voltages to this circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range:

$$V_{SS} < (V_{in} \text{ or } V_{out}) < V_{DD}$$

Unused inputs must always be tied to an appropriate logic voltage level (either  $V_{SS}$  or  $V_{DD}$ ).

### **DC Parameters**

 $V_{DD}$  =  $V_{DDC}$  = 3.3 V ± 10% or 2.5 V ± 5%, over the specified temperature range.

Parameter	Description	Conditions	Min	Тур	Max	Unit
V <sub>IL</sub>	Input Low Voltage	V <sub>DD</sub> = 3.3 V, PECL_CLK single ended	1.49	1	1.825	V
		V <sub>DD</sub> = 2.5 V, PECL_CLK single ended	1.10	-	1.45	
		All other inputs	V <sub>SS</sub>	-	0.8	
V <sub>IH</sub>	Input High Voltage	V <sub>DD</sub> = 3.3 V, PECL_CLK single ended	2.135	-	2.42	V
		V <sub>DD</sub> = 2.5 V, PECL_CLK single ended	1.75	-	2.0	
		All other inputs	2.0	-	$V_{DD}$	
I <sub>IL</sub>	Input Low Current [3]		_	-	-100	μΑ
I <sub>IH</sub>	Input High Current [3]		_	-	100	
$V_{PP}$	Peak-to-Peak Input Voltage PECL_CLK		300	-	1000	mV
V <sub>CMR</sub>	Common Mode Range [4] PECL_CLK	V <sub>DD</sub> = 3.3 V	V <sub>DD</sub> – 2.0	-	$V_{DD} - 0.6$	V
		V <sub>DD</sub> = 2.5 V	V <sub>DD</sub> – 1.2	-	$V_{DD} - 0.6$	
$V_{OL}$	Output Low Voltage [5]	I <sub>OL</sub> = 20 mA	_	-	0.4	V
V <sub>OH</sub>	Output High Voltage [5]	I <sub>OH</sub> = –20 mA, V <sub>DD</sub> = 3.3 V	2.5	ı	_	V
		$I_{OH} = -20 \text{ mA}, V_{DD} = 2.5 \text{ V}$	1.8	ı	_	
I <sub>DDQ</sub>	Quiescent Supply Current		_	5	7	mA
I <sub>DD</sub>	Dynamic Supply Current	V <sub>DD</sub> = 3.3 V, Outputs @ 100 MHz, C <sub>L</sub> = 30 pF	-	180	_	mA
		$V_{DD}$ = 3.3 V, Outputs @ 160 MHz, $C_L$ = 30 pF	-	270	_	
		$V_{DD}$ = 2.5 V, Outputs @ 100 MHz, $C_L$ = 30 pF	-	125	_	
		V <sub>DD</sub> = 2.5 V, Outputs @ 160 MHz, C <sub>L</sub> = 30 pF	-	190	_	
Z <sub>out</sub>	Output Impedance	V <sub>DD</sub> = 3.3 V	12	15	18	Ω
		V <sub>DD</sub> = 2.5 V	14	18	22	
C <sub>in</sub>	Input Capacitance		_	4	_	pF

#### Notes

- 2. **Multiple Supplies:** The voltage on any input or I/O pin cannot exceed the power pin during power-up. Power supply sequencing is not required.
- 3. Inputs have pull-up/pull-down resistors that effect input current.
- 4. The V<sub>CMR</sub> is the difference from the most positive side of the differential input signal. Normal operation is obtained when the "High" input is within the V<sub>CMR</sub> range and the input lies within the V<sub>PP</sub> specification.
- 5. Driving series or parallel terminated 50  $\Omega$  (or 50  $\Omega$  to  $V_{DD}/2)$  transmission lines.



### **Thermal Resistance**

Parameter [6]	Description	Test Conditions	32-pin TQFP	Unit
$\theta_{JA}$	,	Test conditions follow standard test methods and procedures for measuring thermal impedance, in	65	°C/W
$\theta_{JC}$	Thermal resistance (junction to case)	accordance with EIA/JESD51.	12	°C/W

# **AC Parameters**

 $V_{DD}$  =  $V_{DDC}$  = 3.3 V ± 10% or 2.5 V ± 5%, over the specified operating range.

Parameter [7]	Description	Conditions	Min	Тур	Max	Unit
F <sub>max</sub>	Input Frequency [8]	V <sub>DD</sub> = 3.3 V	_	-	200	MHz
		V <sub>DD</sub> = 2.5 V	_	_	170	
T <sub>pd</sub>	PECL_CLK to Q Delay [8]	V <sub>DD</sub> = 3.3 V	4.0	-	8.0	ns
	TCLK to Q Delay [8]		4.4	_	8.9	
	PECL_CLK to Q Delay [8]	V <sub>DD</sub> = 2.5 V	6.0	_	10.0	
	TCLK to Q Delay [8]		6.4	_	10.9	
F <sub>outDC</sub>	Output Duty Cycle [8, 9, 10]	Measured at V <sub>DD</sub> /2	45	_	55	%
t <sub>pZL</sub> , t <sub>pZH</sub>	Output Enable Time (all outputs)		2	_	10	ns
t <sub>pLZ</sub> , t <sub>pHZ</sub>	Output Disable Time (all outputs)		2	_	10	ns
T <sub>skew</sub>	Output-to-Output Skew [8, 10]		_	150	250	ps
T <sub>skew(pp)</sub>	Part-to-Part Skew [11]	PECL_CLK to Q	_	_	1.5	ns
		TCLK to Q	_	_	2.0	
T <sub>s</sub>	Set-up Time [8, 12]	SYNC_OE to PECL_CLK	1.0	_	_	ns
		SYNC_OE to TCLK	0.0	_	_	
T <sub>h</sub>	Hold Time [8, 12]	PECL_CLK to SYNC_OE	0.0	_	_	ns
		TCLK to SYNC_OE	1.0	_	_	
T <sub>r</sub> /T <sub>f</sub>	Output Clocks Rise/Fall Time [10]	0.8 V to 2.0 V, V <sub>DD</sub> = 3.3 V	0.20	_	1.0	ns
		0.6 V to 1.8 V, V <sub>DD</sub> = 2.5 V	0.20	-	1.3	

- Notes
  6. These parameters are guaranteed by design and are not tested.
  7. Parameters are guaranteed by design and characterization. Not 100% tested in production. All parameters specified with loaded outputs.
  8. Outputs driving 50Ω transmission lines.
  9. 50% input duty cycle.
  10. See Figure 3 and Figure 4 on page 7.
  11. Part-to-Part skew at a given temperature and voltage.
  12. Setup and hold times are relative to the falling edge of the input clock.



Figure 3. LVCMOS\_CLK CY29948 Test Reference for  $V_{CC}$  = 3.3 V and  $V_{CC}$  = 2.5 V

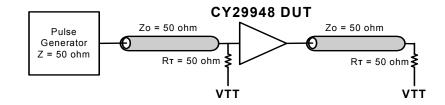


Figure 4. PECL\_CLK CY29948 Test Reference for  $V_{CC}$  = 3.3 V and  $V_{CC}$  = 2.5 V

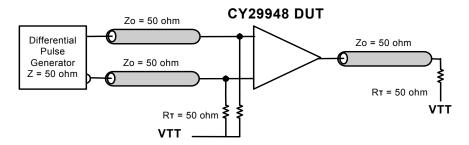


Figure 5. Propagation Delay (t<sub>PD</sub>) Test Reference

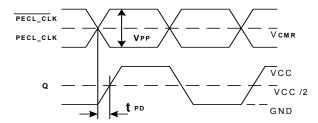


Figure 6. LVCMOS Propagation Delay (tpD) Test Reference

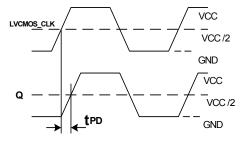




Figure 7. Output Duty Cycle ( $F_{outDC}$ )

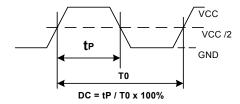
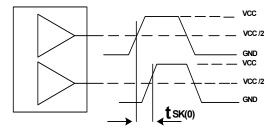


Figure 8. Output-to-Output Skew tsk(0)

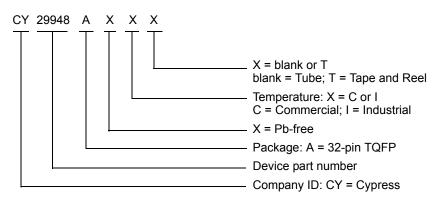




# **Ordering Information**

Part Number	Package Type	Production Flow
Pb-free		
CY29948AXC	32-pin TQFP	Commercial, 0 °C to +70 °C
CY29948AXCT	32-pin TQFP – Tape and Reel	Commercial, 0 °C to +70 °C
CY29948AXI	32-pin TQFP	Industrial, –40 °C to +85 °C
CY29948AXIT	32-pin TQFP – Tape and Reel	Industrial, –40 °C to +85 °C

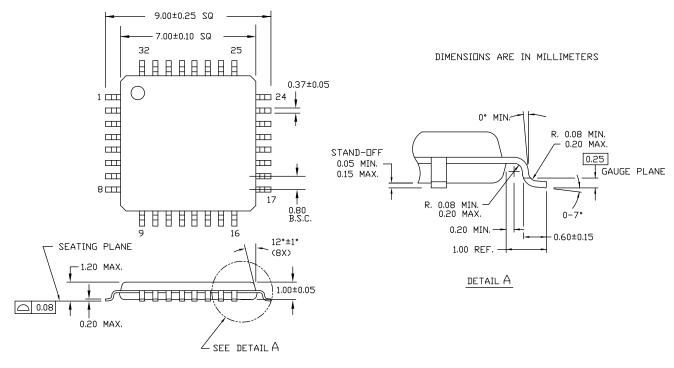
# **Ordering Code Definitions**





# **Package Drawing and Dimensions**

Figure 9. 32-pin TQFP (7 × 7 × 1.0 mm) Package Outline, 51-85063



51-85063 \*E



# **Acronyms**

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
ESD	Electrostatic Discharge
I/O	Input/Output
LVCMOS	Low Voltage Complementary Metal Oxide Semiconductor
LVPECL	Low Voltage Positive Emitter Coupled Logic
LVTTL	Low Voltage Transistor-Transistor Logic
PLL	Phase Locked Loop
TQFP	Thin Quad Flat Pack

# **Document Conventions**

# **Units of Measure**

Symbol	Unit of Measure		
°C	degree Celsius		
kV	kilovolt		
MHz	megahertz		
μA	microampere		
mA	milliampere		
mm	millimeter		
mV	millivolt		
ns	nanosecond		
Ω	ohm		
%	percent		
pF	picofarad		
ps	picosecond		
V	volt		



# **Document Revision History**

	Document Title: CY29948, 2.5 V or 3.3 V, 200 MHz, 1:12 Clock Distribution Buffer Document Number: 38-07288			
Rev.	ECN No.	Submission Date	Orig. of Change	Description of Change
**	111099	02/13/02	BRK	New data sheet.
*A	116782	08/14/02	HWT	Added Commercial Temperature Range
*B	122880	12/22/02	RBI	Added power up requirements to Maximum Ratings
*C	428221	See ECN	RGL	Added Lead-free devices
*D	2904731	04/05/10	CXQ	Removed inactive part numbers - CY29948AI and CY29948AIT. Updated package diagram.
*E	3246222	05/02/2011	CXQ	Added Ordering Code Definitions. Added Acronyms and Units of Measure. Updated in new template.
*F	3859773	01/07/2013	AJU	Updated Ordering Information (Updated part numbers). Updated Package Drawing and Dimensions: spec 51-85063 – Changed revision from *C to *D.
*G	4345036	04/14/2014	XHT	Updated to new template. Completing Sunset Review.
*H	4586288	12/03/2014	XHT Updated Functional Description: Added "For a complete list of related documentation, click here." at the	
*	5275785	05/18/2016	PSR	Added Thermal Resistance. Updated Package Drawing and Dimensions: spec 51-85063 – Changed revision from *D to *E. Updated to new template.



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